

PATENT

IN THE UNITED STATES PATENT OFFICE

In re application of:

Paul J. Rudeck

Kelly T. Hurley

Serial No.: Not Assigned

Filed: November 25, 2003 (Concurrently Herewith)

For: **METHOD AND STRUCTURE FOR AN OXIDE
LAYER OVERLYING AND OXIDATION-
RESISTANT LAYER**

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

§ Group Art Unit: Not Assigned
§ Examiner: Not Assigned
§ Atty. Docket: 1998-0609.02/US
§ Paper No. *

Certificate of Express Mailing (37 CFR §1.10)

"Express Mail" mail number: ET658403234US

Date of Deposit: November 25, 2003

I hereby certify that this paper is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated above and is addressed to the Commissioner for Patents, PO Box 1450, Alexandria, VA 22313-1450.



Signature

INFORMATION DISCLOSURE STATEMENT

In compliance with the duty of disclosure under 37 CFR §1.56, Applicant respectfully requests entry of this Information Disclosure Statement, and that the references listed on the attached Form PTO-1449 be considered by the Examiner and made of record. As the references consist only of patent documents cumulative from the parent, copies are not enclosed.

In accordance with 37 CFR §1.97(b), this Information Disclosure Statement is not to be construed as a representation that a search has been made or that no other possible material information as defined in 37 CFR §1.56(a) exists.

The following references are submitted for the Examiner's review:

U.S. Patent Documents

Document No.	Date	Inventor
4,870,470	09/1989	Bass et al.
5,378,659	01/1995	Roman et al.
5,656,837	08/1997	Lancaster et al.
5,719,410	02/1998	Suehiro et al.
5,781,031	07/1998	Bertin et al.
5,789,295	08/1998	Liu
5,963,806	10/1999	Sung et al.
5,981,403	11/1999	Ma et al.
5,985,771	11/1999	Moore et al.
6,051,511	04/2000	Thakur et al.
6,069,640	05/2000	Kubatzki
6,177,311	01/2001	Kauffman et al.
6,653,683	11/2003	Rudeck et al.

Other References:

Cohen, et al. "A novel double metal structure for voltage programmable links" IEEE Electron Device Letters (Sept. 1992) vol. 13, No. 9, pp. 488-490.

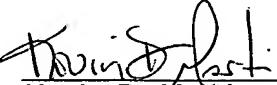
As this Information Disclosure Statement is being submitted before the mailing of a first Office Action on the merits, no fee is due. However, the Commissioner is authorized to charge any required fee to Micron Technology Inc. Deposit Account No.13-3092, Order No. 1998-0609.02/US.

If there are any matters which may be resolved or clarified through telephone interview, the Examiner is respectfully requested to contact Applicant's undersigned agent at the number indicated.

* * * *

A Form PTO-1449 is enclosed herewith.

Respectfully submitted,



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FORM: PTO-1449 (REV: 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	Atty Docket No: 1998-0609.02/US	Serial No: Not Assigned
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (37 CFR 1.98(b))		Applicant: Micron Technology, Inc.	
		Filing Date: November 25, 2003	Group: Not Assigned

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	
	AA 4,870,470	09/1989	Bass et al.	357	23.5	
	AB 5,378,659	01/1995	Roman et al.	437	229	
	AC 5,656,837	08/1997	Lancaster et al.	257	314	
	AD 5,719,410	02/1998	Suehiro et al.	257	77	
	AE 5,781,031	07/1998	Bertin et al.	326	39	
	AF 5,789,295	08/1998	Liu	438	264	
	AG 5,963,806	10/1999	Sung et al.	438	266	
	AH 5,981,403	11/1999	Ma et al.	438	758	
	AI 5,985,771	11/1999	Moore et al.	438	791	
	AJ 6,051,511	04/2000	Thakur et al.	438	791	
	AK 6,069,640	05/2000	Kubatzki	438	652	
	AL 6,177,311	01/2001	Kauffman et al.	438	257	
	AM 6,653,683	11/2003	Rudeck et al.	257	315	

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes	Translation No
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	AO					<input type="checkbox"/>	<input type="checkbox"/>
	AP					<input type="checkbox"/>	<input type="checkbox"/>

Initial

OTHER ART (including author, title, date, pertinent pages, etc.)

AQ	Cohen, et al. "A novel double metal structure for voltage programmable links" IEEE Electron Device Letters (Sept 1992) vol. 13, No.9, pp. 488-490.						
AR							
AS							

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AS		
AT		

Examiner:

Date Considered:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication with applicant.